

PRELIMINARY AMENDMENT

Serial Number: Unknown

Filing Date:

Title: DIFFUSION BARRIER LAYER FOR LEAD FREE PACKAGE SUBSTRATE

Assignee: Intel Corporation

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Dkt: 884.A68US1 (INTEL)

0.2 to 2.5 μm . In some embodiments, the diffusion-retarding layer ranges from 0.5 to 1.0 μm .

Conclusion

The Examiner is invited to telephone Applicant's attorney at (612) 373-6971 to facilitate any further prosecution. If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully Submitted,

KUM F. LEONG ET AL.

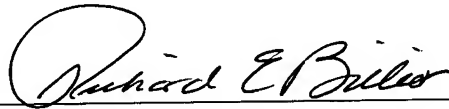
By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Attorneys for Intel Corporation
P.O. Box 2938
Minneapolis, Minnesota 55402
(612) 373-6977

Date

9/29/03

By



Richard E. Billion

Reg. No. 32,836

CERTIFICATE UNDER 37 CFR § 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelop addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 29 day of September 2003

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